



## Final Product Change Notification

201907002F01

**Issue Date:** 23-Dec-2019  
**Effective Date:** 22-Mar-2020

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# QUALITY

### Management Summary

Bump site release of Chipbond-KF (plated bump) for product types in fcQFN (SOT1232)

#### Change Category

- |  |  |  |   |   |
|--|--|--|---|---|
| <input type="checkbox"/> Wafer Fab Process   | <input checked="" type="checkbox"/> Assembly Process   | <input type="checkbox"/> Product Marking           | <input type="checkbox"/> Test Location  | <input type="checkbox"/> Design                         |
| <input type="checkbox"/> Wafer Fab Materials | <input checked="" type="checkbox"/> Assembly Materials | <input type="checkbox"/> Mechanical Specification  | <input type="checkbox"/> Test Process   | <input type="checkbox"/> Errata                         |
| <input type="checkbox"/> Wafer Fab Location  | <input checked="" type="checkbox"/> Assembly Location  | <input type="checkbox"/> Packing/Shipping/Labeling | <input type="checkbox"/> Test Equipment | <input type="checkbox"/> Electrical spec./Test coverage |
| <input type="checkbox"/> Firmware            | <input type="checkbox"/> Other                         |  |   |   |

Bump Site Transfer ASE-KH (Printed Bump) to Chipbond-KF (Plated Bump) for Products in SOT1232 (fcQFN)

### Description of Change

Bump site release of plated bump process of Chipbond-KF for product types in fcQFN (SOT1232) .

#### Reason for Change

Release of plated bump technology is required in view of supply contingency and phasing out of present solder paste and printed bump process technology.

#### Identification of Affected Products

Product identification does not change

### Product Availability

#### Sample Information

Samples are available upon request

#### Production

Planned first shipment 01-Apr-2020

### Anticipated Impact on Form, Fit, Function, Reliability or Quality

No impact on form, fit, function, reliability or quality.

#### Data Sheet Revision

No impact to existing datasheet

## Disposition of Old Products

Existing inventory will be shipped until depleted

As same 12 NC is used, during transition phase as well as plated and printed will be delivered.

## Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by 22-Jan-2020.

## Remarks

Updated PQP are available based on request.

## Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

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NXP Quality Management Team.

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NXP Semiconductors

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## Affected Part Numbers

BGU8019X

BGU8L1X

BGU8M1X

BGU8H1X

LTE3401HX

BGS8H2X

BGS8L2X

BGS8M2X

LTE3401LX

BGU8103X